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Global Tungsten Copper Electronic Packaging Materials Supply, Demand and Key Producers, 2026-2032

https://marketpublishers.com/r/G35875E747FAEN.html
Date: June 2026
Pages: 121
Price: US$ 4,480.00 (Single User License)
ID: G35875E747FAEN

Abstracts

The global Tungsten Copper Electronic Packaging Materials market size is expected to reach $ 1077 million by 2032, rising at a market growth of 5.6% CAGR during the forecast period (2026-2032).

Tungsten copper electronic packaging material is a metal based composite material prepared by powder metallurgy process, which combines the low expansion and high strength of tungsten with the high thermal and electrical conductivity of copper. Its thermal expansion coefficient can be precisely matched with semiconductor materials through component adjustment, effectively solving the thermal management problem in high-power electronic device packaging, and playing an irreplaceable key role in high-end fields such as power semiconductors, 5G communication, optical modules, aerospace, etc. In 2025, global Tungsten Copper Electronic Packaging Materials production reached approximately 4,687 MT, with an average global market price of around US$ 153 per kg.The annual production capacity of tungsten copper electronic packaging materials is 6000 tons, with a gross profit margin of about 35%.

Upstream core raw materials: tungsten powder, copper powder.

Downstream: electronic packaging; Heat sink material; Lead frame; other.

Cost analysis: Raw material costs account for 50-70%; Manufacturing/processing costs account for 15% -25%; Artificial labor and others account for 5% -10%.

In the electronic device packaging industry, tungsten copper electronic packaging materials have become an important material choice for high-power device heat

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dissipation due to their unique thermal management capabilities. This type of material is made by combining the high melting point of tungsten (3422 ?) with the thermal conductivity of copper (about 400W/m ? K), using powder metallurgy or infiltration processes, which can effectively balance the difference in thermal expansion and dissipate heat. After using this material in the power control module of new energy vehicles, the operating temperature of the chip can be reduced by 10-15 ?, and the system stability is significantly enhanced.

The tungsten copper electronic packaging materials currently used in industrial applications are mainly divided into three types. The high tungsten content type usually contains 70-90% tungsten, and its thermal expansion coefficient (6.5-8.5 ? 10 ??/?) is close to that of silicon chips (4 ? 10 ??/?), which can compress the thermal mismatch rate to within 15%. A certain model of substrate material containing 85% tungsten has a thermal conductivity of 180-220W/m ? K. When used in 5G base station power amplifier modules, the thermal resistance can be reduced to 0.2 ?/W, and the efficiency is increased by more than 30% compared to traditional aluminum silicon carbide materials.

This report studies the global Tungsten Copper Electronic Packaging Materials production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Tungsten Copper Electronic Packaging Materials and provides market size (US$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Tungsten Copper Electronic Packaging Materials that contribute to its increasing demand across many markets.

Highlights and key features of the study
Global Tungsten Copper Electronic Packaging Materials total production and demand, 2021-2032, (Tons)
Global Tungsten Copper Electronic Packaging Materials total production value, 2021-2032, (USD Million)
Global Tungsten Copper Electronic Packaging Materials production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Tons), (based on production site)
Global Tungsten Copper Electronic Packaging Materials consumption by region & country, CAGR, 2021-2032 & (Tons)
U.S. VS China: Tungsten Copper Electronic Packaging Materials domestic production,

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consumption, key domestic manufacturers and share
Global Tungsten Copper Electronic Packaging Materials production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Tons)
Global Tungsten Copper Electronic Packaging Materials production by Type, production, value, CAGR, 2021-2032, (USD Million) & (Tons)
Global Tungsten Copper Electronic Packaging Materials production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Tons)

This report profiles key players in the global Tungsten Copper Electronic Packaging Materials market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include ALMT Corp, AMETEK, Negele Hartmetall-Technik GmbH, H.C. Starck Hermsdorf GmbH, ATT Advanced Elemental Materials, Santier, ATTL Advanced Materials, Shaanxi Puwei Electronic Technology, Changsha Saneway Electronic Materials, Luoyang Combat Tungsten & Molybdenum Materials, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Tungsten Copper Electronic Packaging Materials market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US$ Millions), volume (production, consumption) & (Tons) and average price (US$/Kg) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Tungsten Copper Electronic Packaging Materials Market, By Region:

United States

China

Europe

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Japan

South Korea

ASEAN

India

Rest of World

Global Tungsten Copper Electronic Packaging Materials Market, Segmentation by Type:

Copper Content200W/(M.K)

Global Tungsten Copper Electronic Packaging Materials Market, Segmentation by Application:

Electronic Packaging

Heat Sink Material

Lead Frame

Other

Companies Profiled:

ALMT Corp

AMETEK

Negele Hartmetall-Technik GmbH

H.C. Starck Hermsdorf GmbH

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ATT Advanced Elemental Materials

Santier

ATTL Advanced Materials

Shaanxi Puwei Electronic Technology

Changsha Saneway Electronic Materials

Luoyang Combat Tungsten & Molybdenum Materials

Starshining Advanced Materials

Xinchao Wei New Materials Technology

Key Questions Answered:
1. How big is the global Tungsten Copper Electronic Packaging Materials market?
2. What is the demand of the global Tungsten Copper Electronic Packaging Materials market?
3. What is the year over year growth of the global Tungsten Copper Electronic Packaging Materials market?
4. What is the production and production value of the global Tungsten Copper Electronic Packaging Materials market?
5. Who are the key producers in the global Tungsten Copper Electronic Packaging Materials market?
6. What are the growth factors driving the market demand?

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Contents

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3 WORLD MANUFACTURERS COMPETITIVE ANALYSIS

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9 COMPANY PROFILES

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10 INDUSTRY CHAIN ANALYSIS

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List Of Tables

LIST OF TABLES

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List Of Figures

LIST OF FIGURES

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